

Description

The DFS540HF12DFC1 is a Half Bridge SiC MOSFET Power Module. It integrates high performance SiC MOSFET chips and SiC Diode designed for the applications such as Motor drives and Renewable energy.



Features

- Blocking voltage:1200V
- $R_{ds(on)} = 2.9m\Omega$
- Low thermal resistance with Si_3N_4 AMB
- 175°C maximum junction temperature
- 62mm half bridge module

Applications

- Motor Drives
- Vehicle Fast Chargers
- Renewable energy
- UPS

Circuit diagram

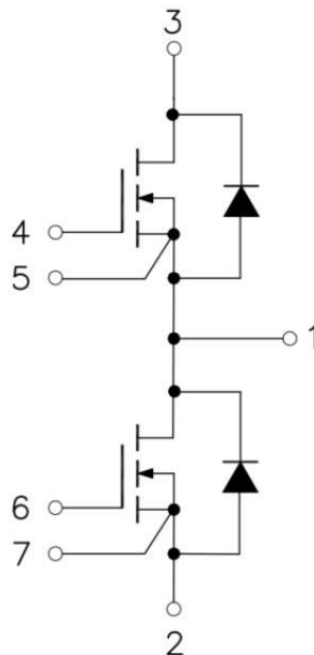


Figure 1. Out drawing & circuit diagram for DFS540HF12DFC1

Pin Configuration and Marking Information

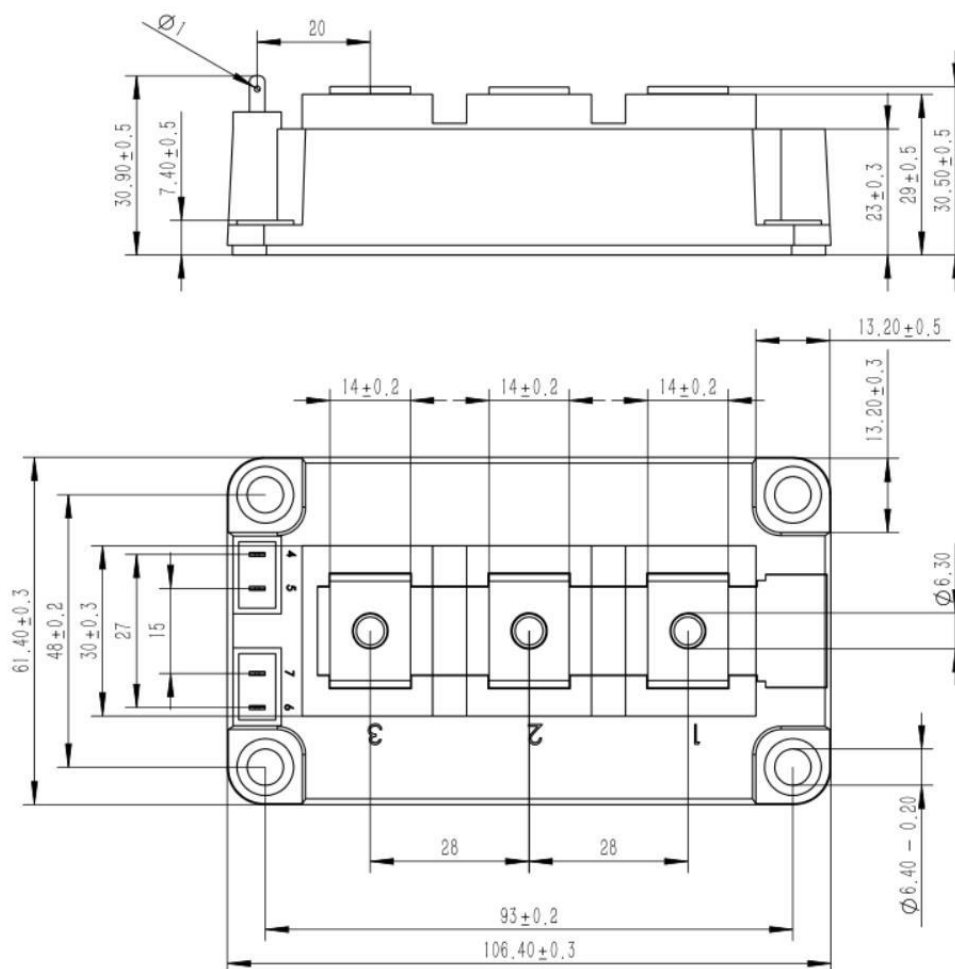


Figure 2. Pin configuration

Module

Parameter	Conditions	Value	Unit
Isolation Voltage	RMS, f=50Hz, t=1min	3.4	kV
Material of module baseplate	-	Cu	-
Creepage distance	terminal to heatsink terminal to terminal	14.5 10	mm

Clearance	terminal to heatsink terminal to terminal	12.5 10	mm
CTI	-	200	-
Module lead resistance, terminals - chip	T _C =25°C	0.6	mΩ
Mounting torque for module mounting	M6	4 to 6	Nm
Weight	-	320	g

Maximum Ratings ($T_j = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Ratings	Unit
V_{DS}	Drain-Source Voltage	G-S Short	1200	V
V_{GS}	Gate-Source Voltage	D-S Short, AC frequency $\geq 1\text{Hz}$, Note1	-10 to 22	V
I_{DS}	DC Continuous Drain Current	$T_c = 25^\circ\text{C}$, $V_{GS} = 18\text{V}$	680	A
I_{DS}	DC Continuous Drain Current	$T_c = 80^\circ\text{C}$, $V_{GS} = 18\text{V}$	540	A
I_{DSM}	Pulse Drain Current	$T_c = 25^\circ\text{C}$, Pulse width = 1ms, $V_{GS} = 18\text{V}$, Note2	1080	A
I_F	Forward Current (Diode)	$T_c = 25^\circ\text{C}$, with ON signal	700	A
I_F	Forward Current (Diode)	$T_c = 80^\circ\text{C}$, with ON signal	560	A
I_{FRM}	Pulse Forward Current (Diode)	Less than 1ms, Note2	1080	A
P_{tot}	Total Power Dissipation	$T_c = 25^\circ\text{C}$	2140	W
T_{jmax}	Max Junction Temperature	-	175	$^\circ\text{C}$
T_{stg}	Storage Temperature	-	-40 to 125	$^\circ\text{C}$

Note1: Recommended Operating Value, +18V/-5V, +18V/-4V, +15V/-4V

Note2: Pulse width limited by maximum junction temperature

SiC SBD Electrical characteristics ($T_j = 25^\circ\text{C}$ unless otherwise specified, chip)

Symbol	Item	Condition		Value			Unit
				Min.	Typ.	Max	
V _F	Diode Forward Voltage	I _F =540A, V _{GS} =0V	T _j =25°C	-	1.85	-	V
			T _j =150°C	-	2.65	-	
t _{rr}	Diode Reverse Recovery Time	(Switch side) V _{DD} =600V, I _D =540A V _{GS} =+18V/-4V	T _j =25°C		27		ns
			T _j =150°C		29		
I _{RM}	Peak reverse recovery Current	R _{gon} /R _{goff} =3.3Ω/3.3Ω (FRD side) V _{RR} =600V, I _F =540A V _{GS} =+18V/-4V	T _j =25°C	-	292	-	A
			T _j =150°C	-	331	-	
Q _{rr}	Recovered charge		T _j =25°C	-	3.5	-	uC
			T _j =150°C	-	4.5	-	

E _{rr}	Reverse recovered energy	Inductive load switching operation	T _j =25°C	-	1.3	-	mJ
			T _j =150°C	-	2.2	-	
R _{th(j-c)}	Thermal Resistance, Junction to Case (Diode)			-	0.065	-	°C/W

MOSFET Electrical characteristics (T_j=25°C unless otherwise specified, chip)

Symbol	Item	Condition		Value			Unit	
				Min.	Typ.	Max		
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =600uA		1200	-	-	V	
I _{DSS}	Zero gate voltage drain Current	V _{DS} =1200V, V _{GS} =0V		-	6	-	μA	
V _{GS(th)}	Gate-source threshold Voltage	I _D =210mA, V _{DS} =V _{GS}	T _j =25°C	1.8	2.7	-	V	
			T _j =175°C	-	2.05	-	V	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =20V, V _{DS} =0V	T _j =25°C	-	-	600	nA	
R _{DS(on)} (Chip)	Static drain-source On-state resistance	I _D =540A V _{GS} =+15V	T _j =25°C	-	3.5	-	mΩ	
			T _j =175°C	-	5.0	-	mΩ	
		I _D =540A V _{GS} =+18V	T _j =25°C	-	2.9	-	mΩ	
			T _j =175°C	-	4.3	-	mΩ	
V _{DS(on)} (Chip)	Static drain-source On-state Voltage	I _D =540A V _{GS} =+15V	T _j =25°C	-	1.89	-	V	
			T _j =175°C	-	2.70	-	V	
		I _D =540A V _{GS} =+18V	T _j =25°C	-	1.57	-	V	
			T _j =175°C	-	2.32	-	V	
C _{iss}	Input Capacitance	V _D =800V, V _{GS} =0V, f =100kHz, V _{AC} =25mV		-	34890	-	pF	
C _{oss}	Output Capacitance			-	1062	-	pF	
C _{rss}	Reverse transfer Capacitance			-	86	-	pF	
R _{Gint}	Internal gate resistor	f =100kHz, V _{AC} =25mV		-	1.1	-	Ω	
Q _g	Total gate charge	V _{DD} =800V, I _D =360A, V _{GS} =+18/-4V		-	1210	-	nC	
t _{d(on)}	Turn-on delay time	V _{DD} =600V I _D =540A V _{GS} =+18/-4V R _{gon} /R _{goff} =2.2Ω/2.2Ω	T _j =25°C	-	72	-	ns	
			T _j =150°C	-	65	-		
t _r	Rise time		T _j =25°C	-	42	-	ns	
			T _j =150°C	-	38	-		
t _{d(off)}	Turn-off delay time		I _D =540A	T _j =25°C	-	152	-	ns
			V _{GS} =+18/-4V	T _j =150°C	-	173	-	
t _f	Fall time			T _j =25°C	-	43	-	ns

		Inductive load switching operation	$T_j = 150^{\circ}\text{C}$	-	48	-	
E_{on}	Turn-on power dissipation		$T_j = 25^{\circ}\text{C}$	-	7.5	-	mJ
			$T_j = 150^{\circ}\text{C}$	-	4.9	-	
E_{off}	Turn-off power dissipation		$T_j = 25^{\circ}\text{C}$	-	9.8	-	mJ
			$T_j = 150^{\circ}\text{C}$	-	10.5	-	
$R_{th(j-c)}$	FET Thermal Resistance	Junction to Case		-	0.07	-	$^{\circ}\text{C} / \text{W}$

Test Conditions

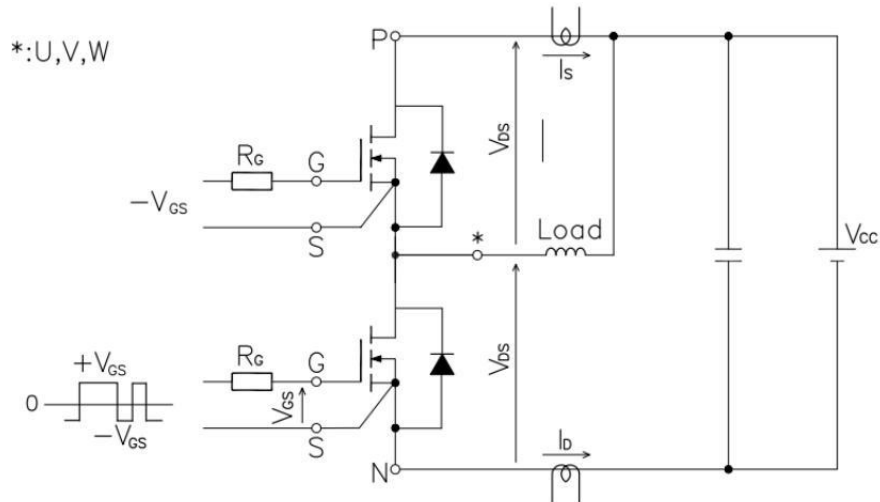


Figure 3. Switching time measure circuit

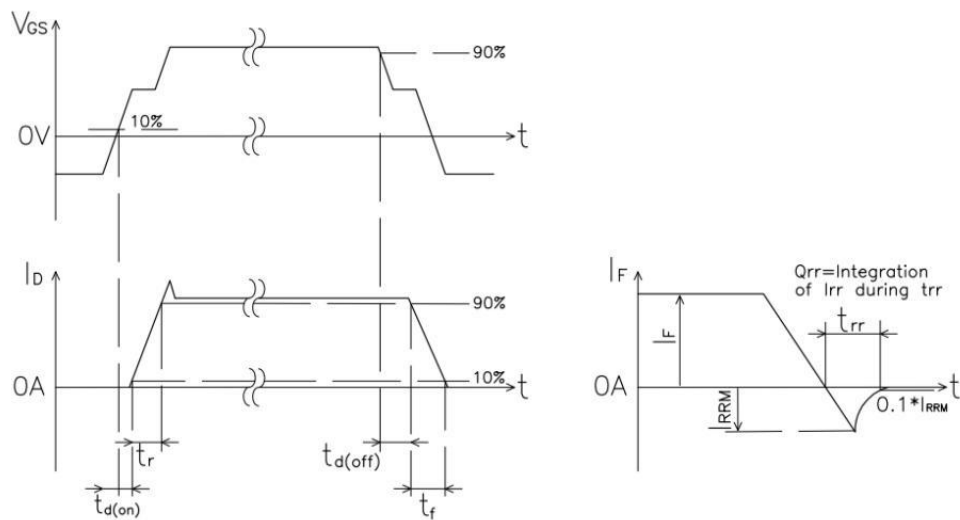


Figure 4. Switching time definition

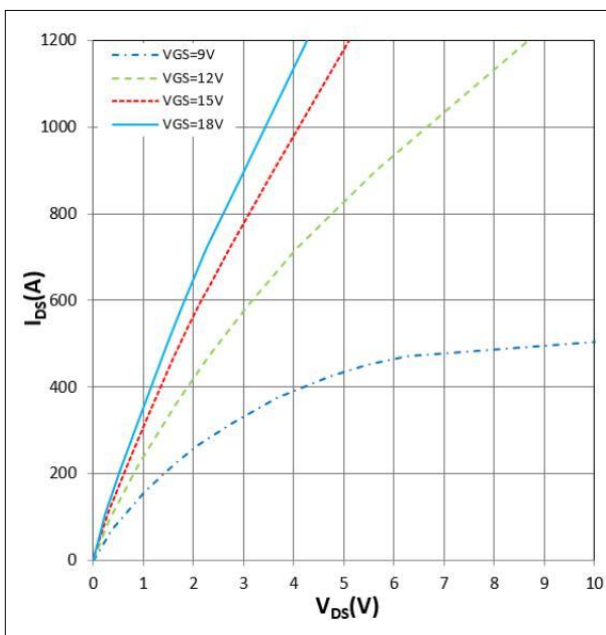


Figure 5. I_{DS} vs V_{DS}

$T_j = 25^\circ\text{C}$

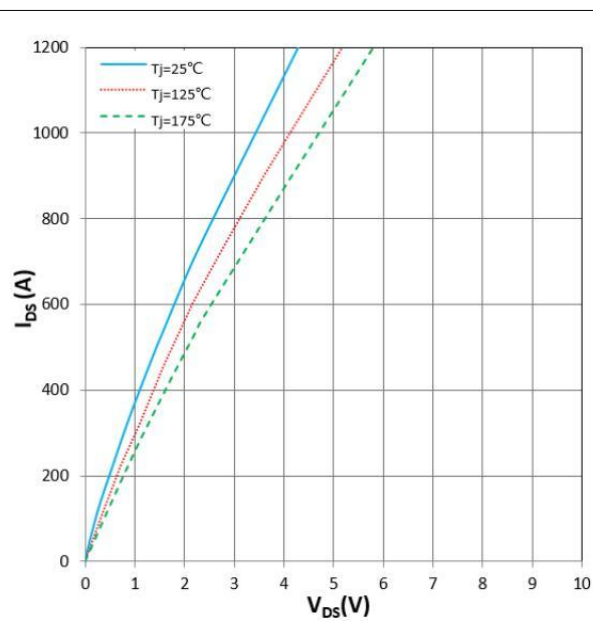


Figure 6. I_{DS} vs V_{DS}

$V_{GS} = +18\text{V}$

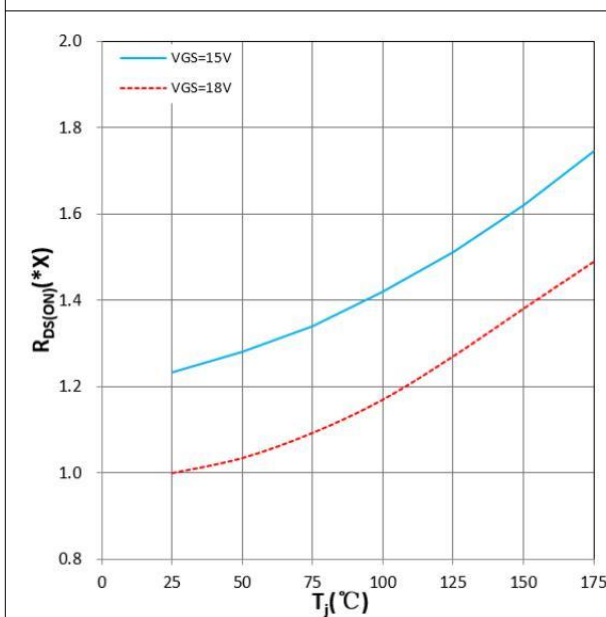


Figure 7. $R_{DS(ON)}$ vs T_j

$V_{GS} = +15\text{V}/+18\text{V}$, $I_D = 540\text{A}$, $1.0X = 2.9\text{m}\Omega$

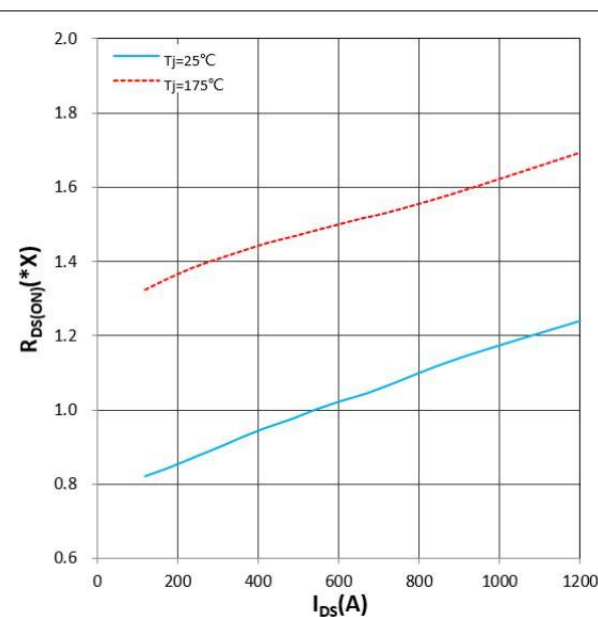


Figure 8. $R_{DS(ON)}$ vs I_{DS}

$V_{GS} = +15\text{V}$, $1.0X = 2.9\text{m}\Omega$

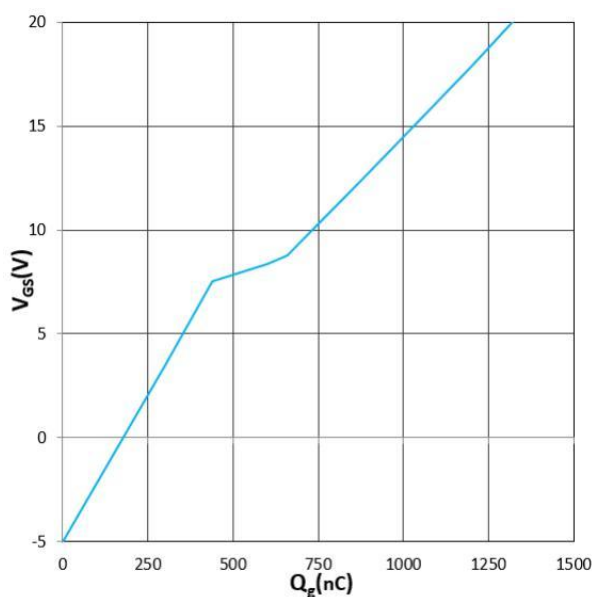


Figure 9. V_{GS} vs Q_g

$V_{DS}=800V$, $I_D=360A$, $T_j=25^\circ C$

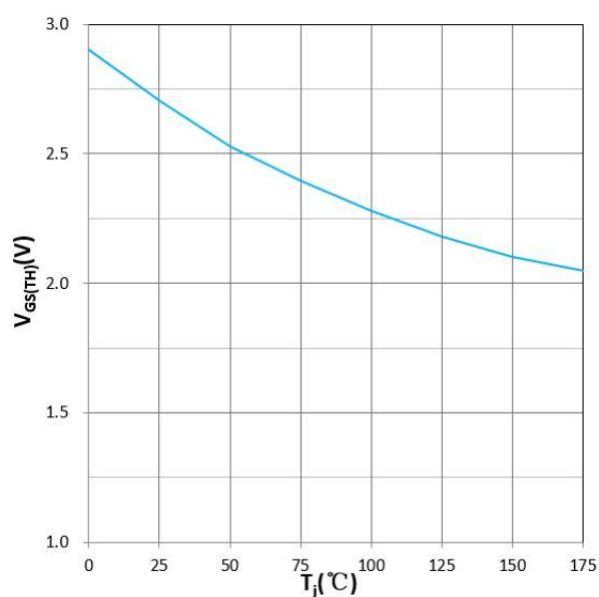


Figure 10. $V_{GS(TH)}$ vs T_j

$V_{GS}=V_{DS}$, $I_D=210mA$

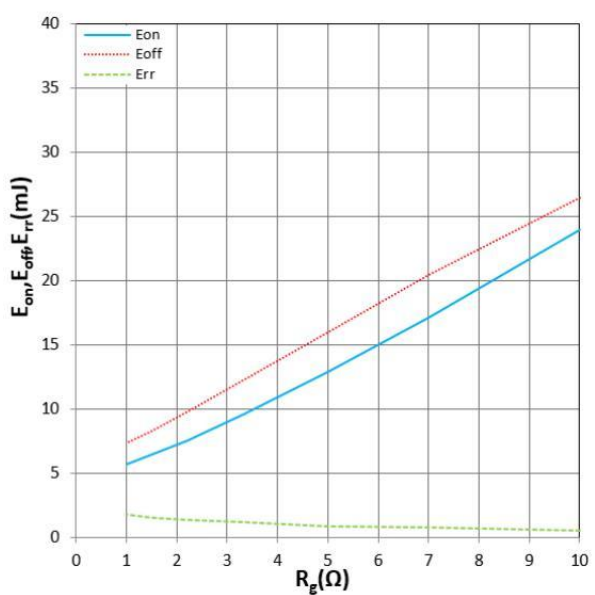


Figure 11. E_{on} , E_{off} , E_{rr} vs R_g

$T_j=25^\circ C$, $V_{DD}=600V$, $V_{GS}=+18V/-4V$, $I_D=540A$

Inductive Load

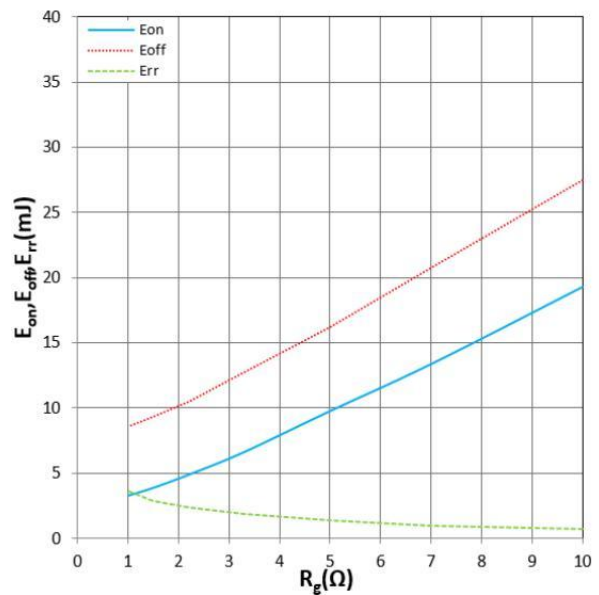


Figure 12. E_{on} , E_{off} , E_{rr} vs R_g

$T_j=150^\circ C$, $V_{DD}=600V$, $V_{GS}=+18V/-4V$, $I_D=540A$

Inductive Load

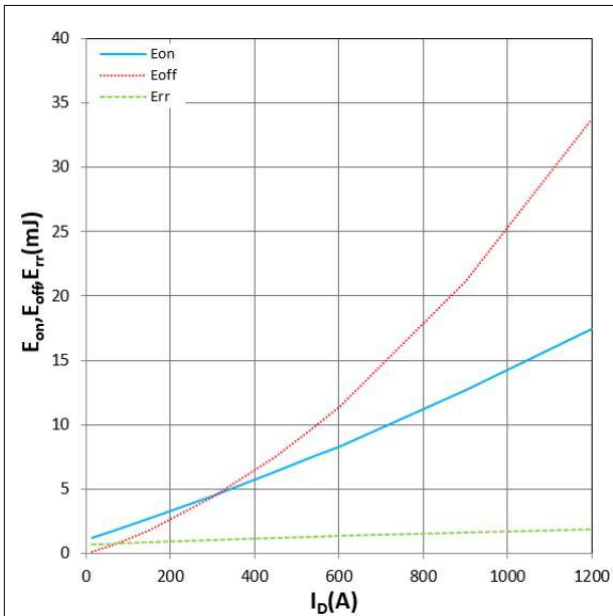


Figure 13. Eon, Eoff, Err vs ID

Tj=25°C, VDD =600V, VGS =+18V/-4V
Rgon/Rgoff =2.2Ω/2.2Ω, Inductive Load

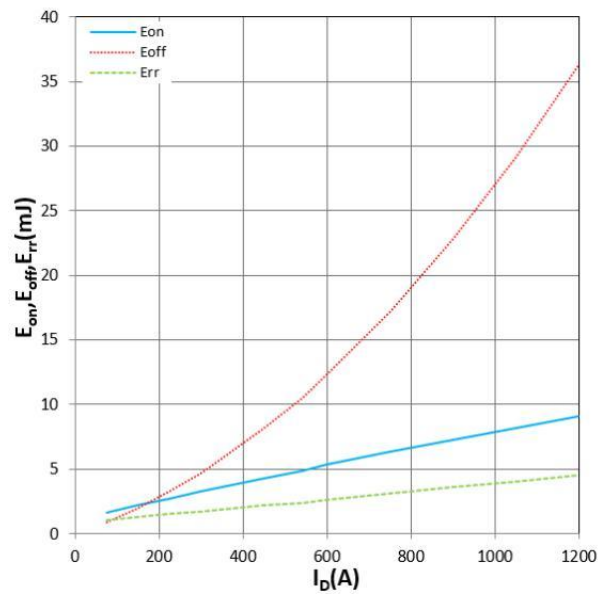


Figure 14. Eon, Eoff, Err vs ID

Tj=150°C, VDD =600V, VGS =+18V/-4V
Rgon/Rgoff =2.2Ω/2.2Ω, Inductive Load

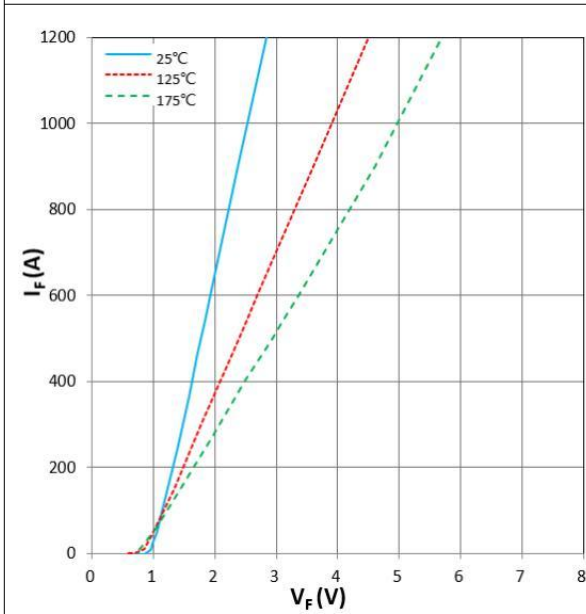


Figure 15. IF vs VF

VGS =0V

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